# **IGBT - Ultra Field Stop**

## FGH40T120SQDNL4

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Ultra Field Stop Trench construction, and provides superior performance in demanding switching applications, offering both low on–state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

#### **Features**

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- These are Pb-Free Devices

#### **Typical Applications**

- Solar Inverter
- Uninterruptible Power Inverter Supplies (UPS)
- Welding

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	V <sub>CES</sub>	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I <sub>C</sub>	160 40	Α
Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>CM</sub>	160	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I <sub>F</sub>	160 40	A
Diode pulsed current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>FM</sub>	160	Α
Gate-emitter voltage Transient gate-emitter voltage ( $T_{pulse} = 5 \mu s$ , D < 0.10)	V <sub>GE</sub>	±20 ±30	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	454 227	W
Operating junction temperature range	TJ	-55 to +175	°C
Storage temperature range	T <sub>stg</sub>	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

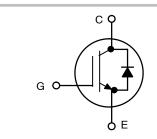
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

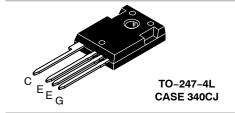


ON Semiconductor®

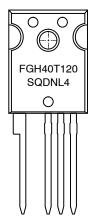
www.onsemi.com

40 A, 1200 V V<sub>CEsat</sub> = 1.7 V E<sub>off</sub> = 1.1 mJ





#### **MARKING DIAGRAM**



#### **ORDERING INFORMATION**

Device	Package	Shipping
FGH40T120SQDNL4	TO-247 (Pb-Free)	30 Units / Rail

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{\theta JC}$	0.33	°C/W
Thermal resistance junction-to-case, for Diode	$R_{\theta JC}$	0.61	°C/W
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	°C/W

#### ELECTRICAL CHARACTERISTICS (T<sub>.I</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	1 .co. conditions		l	٠,٢٢	ax	J
		T .,	4000	ı		
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, } I_{C} = 500 \mu\text{A}$	V <sub>(BR)CES</sub>	1200 1250*	-	ı	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C		- -	1.78 2.3	1.95 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 400 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J</sub> = 175°C	I <sub>CES</sub>	- -	_ 0.6	0.4 -	mA
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V , V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	200	nA
* Guaranteed by design.			ı	ı		
Input capacitance		C <sub>ies</sub>	_	5000	_	pF
Output capacitance	V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	_	140	-	·
Reverse transfer capacitance		C <sub>res</sub>	_	80	_	
Gate charge total		Qg	_	221	_	nC
Gate to emitter charge	V <sub>CE</sub> = 600 V, I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>	_	52	_	° -
Gate to collector charge	1	Q <sub>gc</sub>	_	100	_	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD	. 90				
Turn-on delay time		t <sub>d(on)</sub>	_	46	_	ns
Rise time	1	t <sub>r</sub>	_	33	-	
Turn-off delay time	T <sub>J</sub> = 25°C	t <sub>d(off)</sub>	_	220	-	
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 40 \text{ A}$ $R_{g} = 10 \Omega$	t <sub>f</sub>	_	56	-	
Turn-on switching loss	$V_{GE} = 0 \text{ to } 15V$	E <sub>on</sub>	-	1.4	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	1.1	-	
Total switching loss		E <sub>ts</sub>	-	2.5	-	
Turn-on delay time		t <sub>d(on)</sub>	-	47	-	ns
Rise time	1	t <sub>r</sub>	_	33	-	
Turn-off delay time	T <sub>J</sub> = 175°C	t <sub>d(off)</sub>	_	240	-	
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 40 \text{ A}$ $R_{q} = 10 \Omega$	t <sub>f</sub>	_	132	-	
Turn-on switching loss	V <sub>GE</sub> = 0 to 15 V	E <sub>on</sub>	-	2.7	-	mJ
Turn-off switching loss	1	E <sub>off</sub>	_	1.8	-	
Total switching loss	1	E <sub>ts</sub>	_	4.5	-	
DIODE CHARACTERISTIC						
Forward voltage	V <sub>GE</sub> = 0 V, I <sub>F</sub> = 40 A V <sub>GE</sub> = 0 V, I <sub>F</sub> = 40 A, T <sub>J</sub> = 175°C	V <sub>F</sub>	_ _	3.4 3.1	3.8	V
Reverse recovery time	T <sub>J</sub> = 25°C	t <sub>rr</sub>	_	166	-	ns
Reverse recovery charge	$I_F = 40 \text{ A}, V_R = 400 \text{ V}$	Q <sub>rr</sub>	_	0.78	-	μс
Reverse recovery current	di <sub>F</sub> /dt = 500 A/μs	I <sub>rrm</sub>	_	9.0	-	Α
Reverse recovery time	T <sub>.1</sub> = 125°C	t <sub>rr</sub>	_	390	-	ns
Reverse recovery charge	$I_F = 40 \text{ A}, V_R = 400 \text{ V}$	Q <sub>rr</sub>	_	4.0	-	μс
Reverse recovery current	di <sub>F</sub> /dt = 500 A/μs	I <sub>rrm</sub>	_	20	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

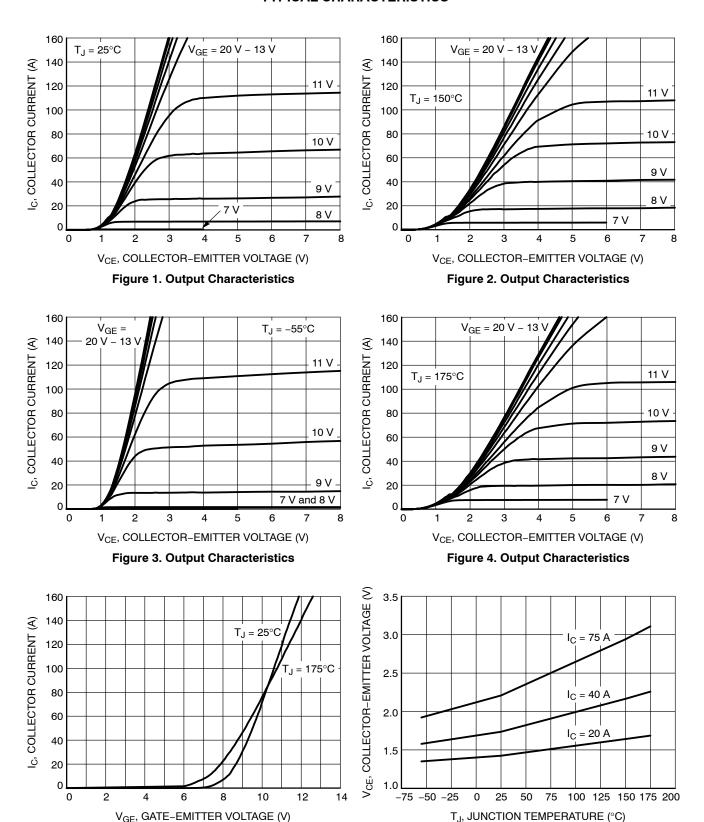


Figure 6. V<sub>CE(sat)</sub> vs. T<sub>J</sub>

Figure 5. Typical Transfer Characteristics

#### **TYPICAL CHARACTERISTICS**

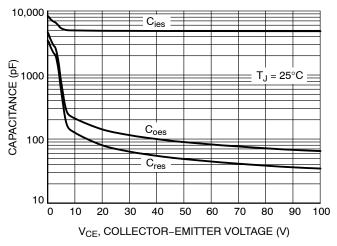


Figure 7. Typical Capacitance

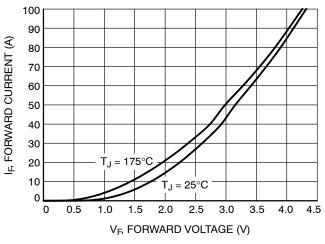


Figure 8. Diode Forward Characteristics

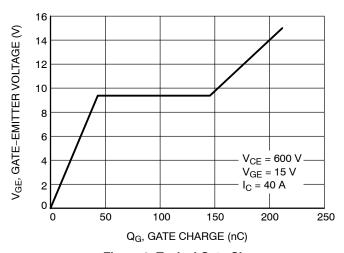


Figure 9. Typical Gate Charge

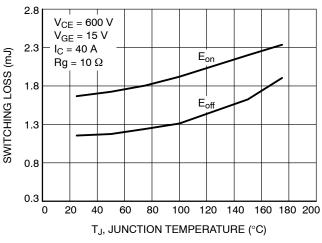


Figure 10. Switching Loss vs. Temperature

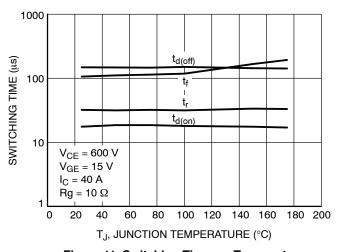


Figure 11. Switching Time vs. Temperature

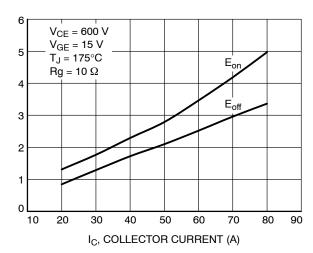


Figure 12. Switching Loss vs. IC

SWITCHING LOSS (mJ)

#### **TYPICAL CHARACTERISTICS**

SWITCHING LOSS (mJ)

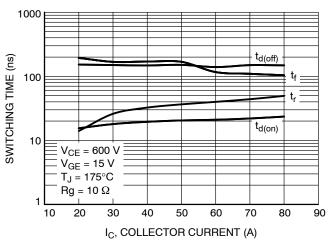


Figure 13. Switching Time vs. IC

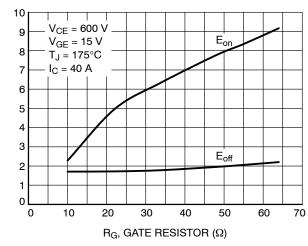


Figure 14. Switching Loss vs. RG

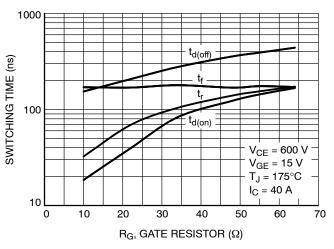


Figure 15. Switching Time vs. RG

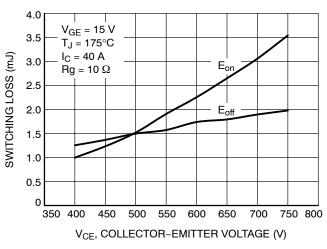


Figure 16. Switching Loss vs. V<sub>CE</sub>

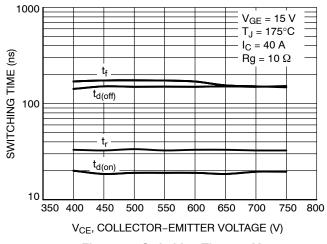


Figure 17. Switching Time vs. V<sub>CE</sub>

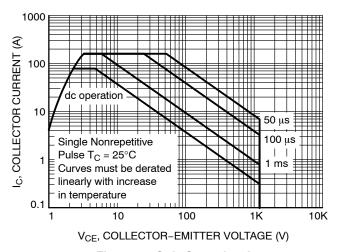
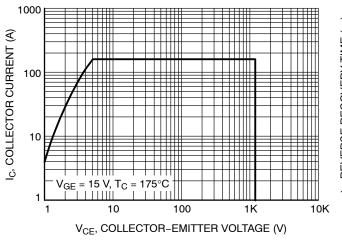


Figure 18. Safe Operating Area

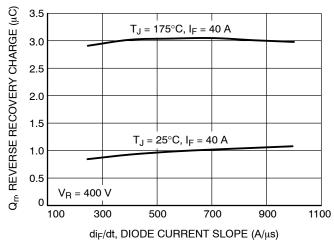
#### **TYPICAL CHARACTERISTICS**



350 V<sub>R</sub> = 400 V trn REVERSE RECOVERY TIME (ns) 300 250 T<sub>.I</sub> = 175°C, I<sub>F</sub> = 40 A 200 150 100  $T_J=25^{\circ}C,\,I_F=40\;A$ 50 100 300 500 700 900 1100  $di_F/dt$ , DIODE CURRENT SLOPE (A/ $\mu$ s)

Figure 19. Reverse Bias Safe Operating Area

Figure 20. t<sub>rr</sub> vs. di<sub>F</sub>/dt



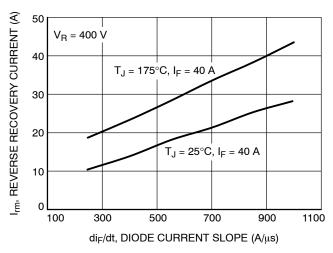


Figure 21. Q<sub>rr</sub> vs. di<sub>F</sub>/dt

Figure 22. I<sub>rm</sub> vs. di<sub>F</sub>/dt

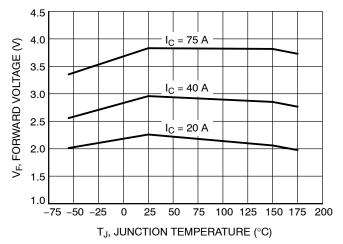


Figure 23. V<sub>F</sub> vs. T<sub>J</sub>

#### **TYPICAL CHARACTERISTICS**

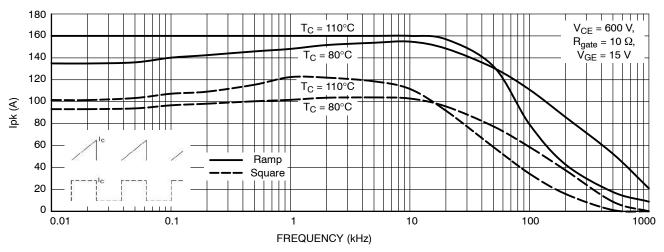


Figure 24. Collector Current vs. Switching Frequency

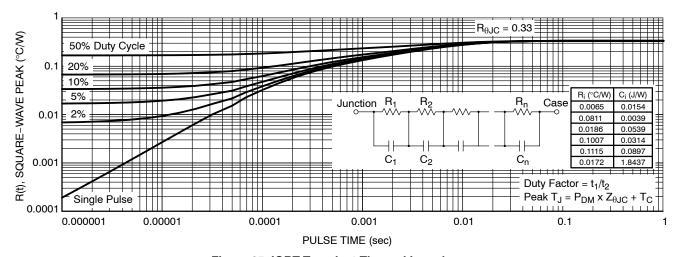


Figure 25. IGBT Transient Thermal Impedance

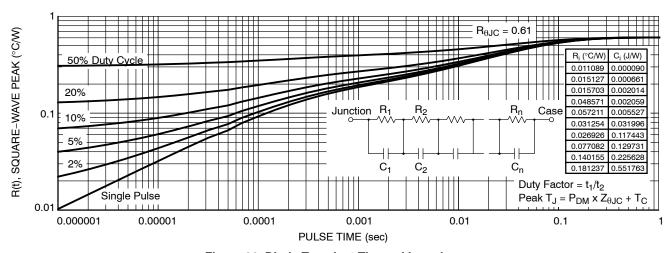


Figure 26. Diode Transient Thermal Impedance

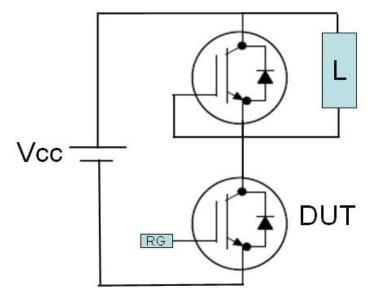


Figure 27. Test Circuit for Switching Characteristics

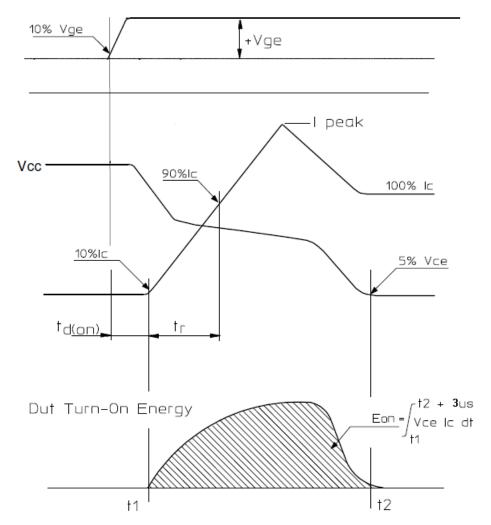


Figure 28. Definition of Turn On Waveform

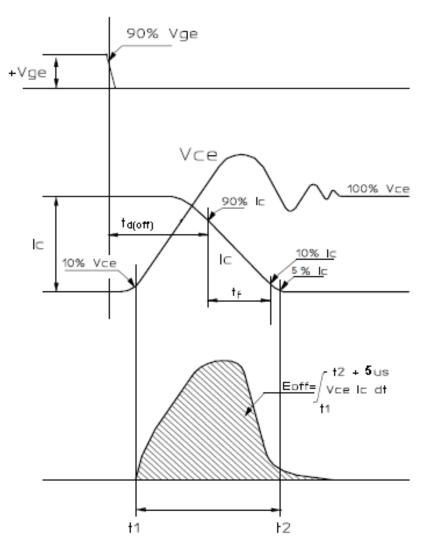
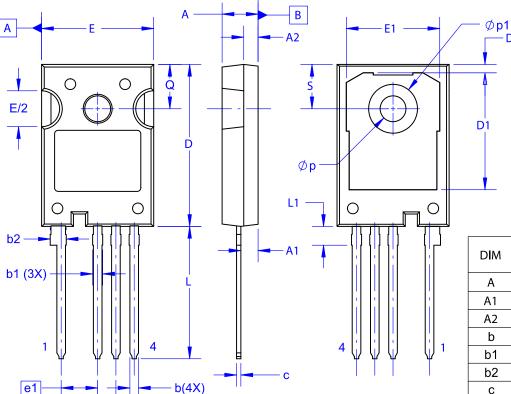


Figure 29. Definition of Turn Off Waveform

#### TO-247-4LD CASE 340CJ **ISSUE A**

**DATE 16 SEP 2019** 

D2



#### NOTES:

e 2X-0.254 M

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
  B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
  FLASH, AND TIE BAR EXTRUSIONS.
  C. ALL DIMENSIONS ARE IN MILLIMETERS.
  D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.10	2.40	2.70
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b1	1.20	1.40	1.60
b2	2.02	2.22	2.42
С	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.25	16.50
D2	0.97	1.17	1.37
е	2.54 BSC		
e1	5.08 BSC		
E	15.40	15.60	15.80
E1	12.80	13.00	13.20
E/2	4.80	5.00	5.20
L	18.22	18.42	18.62
L1	2.42	2.62	2.82
р	3.40	3.60	3.80
p1	6.60	6.80	7.00
Q	5.97	6.17	6.37
S	5.97	6.17	6.37

**MILLIMETERS** 

DOCUMENT NUMBER:	98AON13852G	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	TO-247-4LD		PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales